

10 kPa On-Chip Temperature Compensated & Calibrated Silicon Pressure Sensors

The MPX2010/MPXV2010G series silicon piezoresistive pressure sensors provide a very accurate and linear voltage output directly proportional to the applied pressure. These sensors house a single monolithic silicon die with the strain gauge and thin film resistor network integrated on each chip. The sensor is laser trimmed for precise span, offset calibration and temperature compensation.

Features

- Temperature Compensated over 0°C to +85°C
- Ratiometric to Supply Voltage
- Differential and Gauge Options

Typical Applications

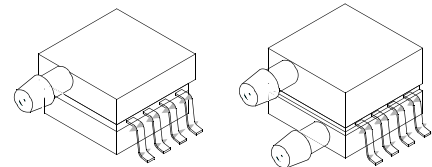
- Respiratory Diagnostics
- Air Movement Control
- Controllers
- Pressure Switching

ORDERING INFORMATION					
Device Type	Options	Case No.	MPX Series Order No.	Packing Options	Device Marking
SMALL OUTLINE PACKAGE (MPXV2010G SERIES)					
Ported Elements	Gauge, Side Port, SMT	1369	MPXV2010GP	Trays	MPXV2010G
	Differential, Dual Port, SMT	1351	MPXV2010DP	Trays	MPXV2010G
UNIBODY PACKAGE (MPX2010 SERIES)					
Basic Element	Differential	344	MPX2010D	—	MPX2010D
Ported Elements	Differential, Dual Port	344C	MPX2010DP	—	MPX2010DP
	Gauge	344B	MPX2010GP	—	MPX2010GP
	Gauge, Axial	344E	MPX2010GS	—	MPX2010D
	Gauge, Axial PC Mount	344F	MPX2010GSX	—	MPX2010D

MPX2010 MPXV2010G SERIES

**COMPENSATED
PRESSURE SENSOR**
0 to 10 kPa (0 to 1.45 psi)
FULL SCALE SPAN: 25 mV

SMALL OUTLINE PACKAGES



MPXV2010GP
CASE 1369-01

MPXV2010DP
CASE 1351-01

SMALL OUTLINE PACKAGE PIN NUMBERS

1	GND ⁽¹⁾	5	N/C
2	+V _{OUT}	6	N/C
3	V _S	7	N/C
4	-V _{OUT}	8	N/C

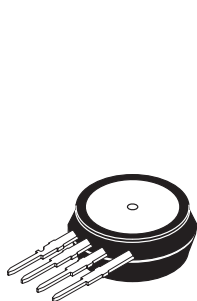
1. Pin 1 in noted by the notch in the lead.

UNIBODY PACKAGE PIN NUMBERS

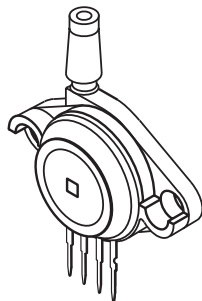
1	GND ⁽¹⁾	3	V _S
2	+V _{OUT}	4	-V _{OUT}

1. Pin 1 in noted by the notch in the lead.

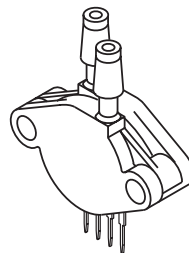
UNIBODY PACKAGES



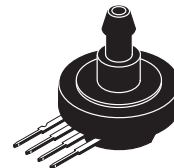
MPX2010GP
CASE 344-15



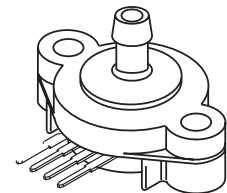
MPX2010GP
CASE 344B-01



MPX2010DP
CASE 344C-01



MPX2010GS
CASE 344E-01



MPX2010GSX
CASE 344F-01

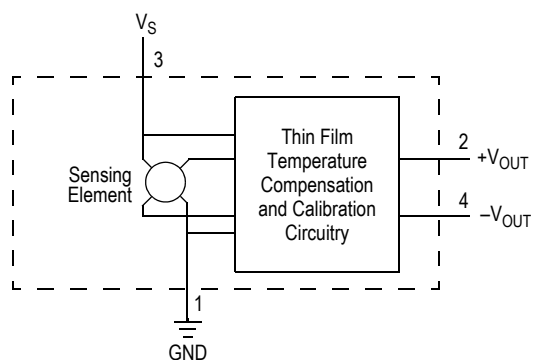


Figure 1. Temperature Compensated and Calibrated Pressure Sensor Schematic

VOLTAGE OUTPUT VERSUS APPLIED DIFFERENTIAL PRESSURE

The output voltage of the differential or gauge sensor increases with increasing pressure applied to the pressure side (P1) relative to the vacuum side (P2). Similarly, output

voltage increases as increasing vacuum is applied to the vacuum side (P2) relative to the pressure side (P1).

Figure 1 shows a block diagram of the internal circuitry on the stand-alone pressure sensor chip.

Table 1. Maximum Ratings⁽¹⁾

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	P_{MAX}	75	kPa
Storage Temperature	T_{STG}	-40 to +125	°C
Operating Temperature	T_A	-40 to +125	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Table 2. Operating Characteristics ($V_S = 10 V_{DC}$, $T_A = 25^\circ C$ unless otherwise noted, $P_1 > P_2$)

Characteristic	Symbol	Min	Typ	Max	Units
Pressure Range ⁽¹⁾	P_{OP}	0	—	10	kPa
Supply Voltage ⁽²⁾	V_S	—	10	16	V_{DC}
Supply Current	I_O	—	6.0	—	mA _{dc}
Full Scale Span ⁽³⁾	V_{FSS}	24	25	26	mV
Offset ⁽⁴⁾	V_{OFF}	-1.0	—	1.0	mV
Sensitivity	$\Delta V/\Delta P$	—	2.5	—	mV/kPa
Linearity ⁽⁵⁾	—	-1.0	—	1.0	% V_{FSS}
Pressure Hysteresis ⁽⁵⁾ (0 to 50 kPa)	—	—	±0.1	—	% V_{FSS}
Temperature Hysteresis ⁽⁵⁾ (-40°C to +125°C)	—	—	±0.5	—	% V_{FSS}
Temperature Effect on Full Scale Span ⁽⁵⁾	TCV_{FSS}	-1.0	—	1.0	% V_{FSS}
Temperature Effect on Offset ⁽⁵⁾	TCV_{OFF}	-1.0	—	1.0	mV
Input Impedance	Z_{IN}	1000	—	2550	W
Output Impedance	Z_{OUT}	1400	—	3000	W
Response Time ⁽⁶⁾ (10% to 90%)	t_R	—	1.0	—	ms
Warm-Up Time	—	—	2.0	—	ms
Offset Stability ⁽⁷⁾	—	—	±0.5	—	% V_{FSS}

- 1.0 kPa (kiloPascal) equals 0.145 psi.
- Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self-heating.
- Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum related pressure.
- Offset (V_{OFF}) is defined as the output voltage at the minimum rated pressure.
- Accuracy (error budget) consists of the following:
 - Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.
 - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
 - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C.
 - TcSpan: Output deviation over the temperature range of 0° to 85°C, relative to 25°C.
 - TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0° to 85°C, relative to 25°C.
 - Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of V_{FSS} , at 25°C.
- Response Time is defined as the time from the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
- Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

ON-CHIP TEMPERATURE COMPENSATION AND CALIBRATION

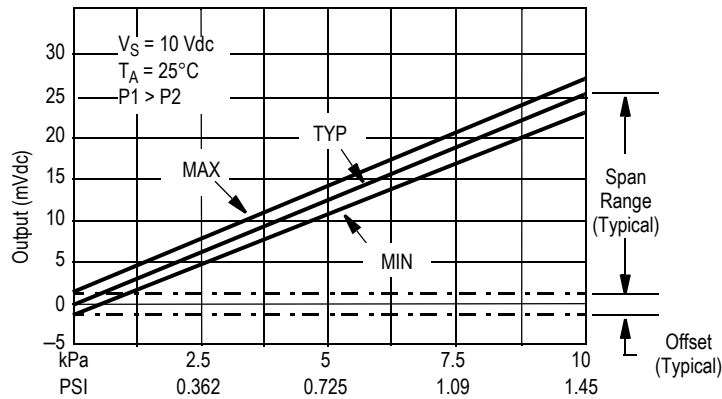


Figure 2. Output vs. Pressure Differential

Figure 2 shows the output characteristics of the MPX2010/MPXV2010G series at 25°C. The output is directly proportional to the differential pressure and is essentially a straight line.

The effects of temperature on full scale span and offset are very small and are shown under Operating Characteristics.

This performance over temperature is achieved by having both the shear stress strain gauge and the thin-film resistor circuitry on the same silicon diaphragm. Each chip is dynamically laser trimmed for precise span and offset calibration and temperature compensation.

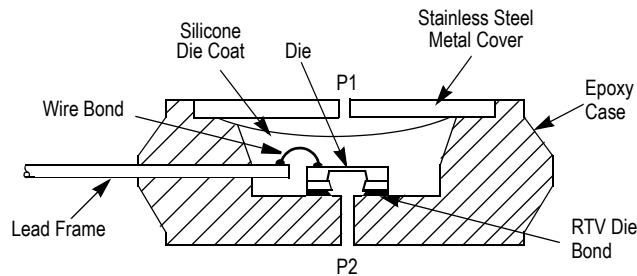


Figure 3. Unibody Package: Cross Sectional Diagram (Not to Scale)

Figure 3 illustrates the differential/gauge die in the basic chip carrier (Case 344). A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

The MPX2010/MPXV2010G series pressure sensor operating characteristics and internal reliability and

qualification tests are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor performance and long term reliability. Contact the factory for information regarding media compatibility in your application.

LINEARITY

Linearity refers to how well a transducer's output follows the equation: $V_{out} = V_{off} + \text{sensitivity} \times P$ over the operating pressure range. There are two basic methods for calculating nonlinearity: (1) end point straight line fit (see Figure 4) or (2) a least squares best line fit. While a least squares fit gives the "best case" linearity error (lower numerical value), the calculations required are burdensome.

Conversely, an end point fit will give the "worst case" error (often more desirable in error budget calculations) and the calculations are more straightforward for the user. Freescale's specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

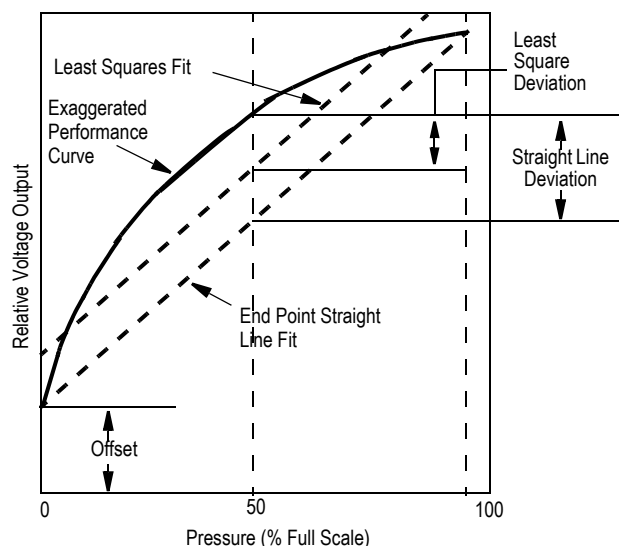


Figure 4. Linearity Specification Comparison

PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

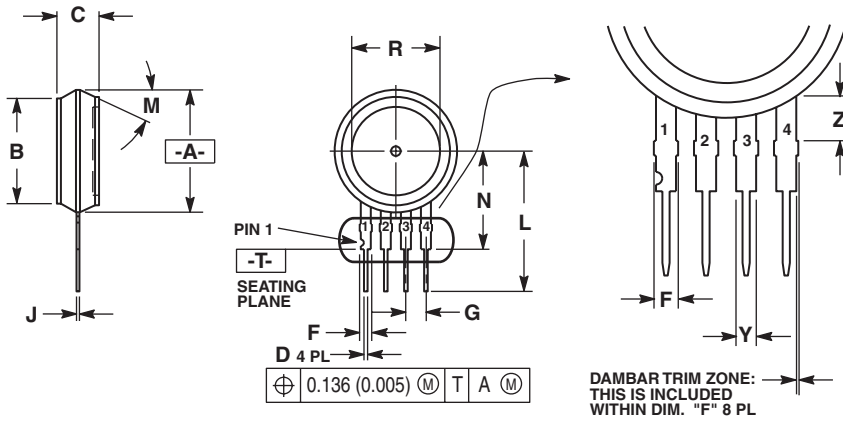
Freescale designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing silicone gel which isolates the die from the environment. The Freescale MPX pressure sensor is designed to operate with positive differential pressure applied, $P1 > P2$.

The Pressure (P1) side may be identified by using the following table.

Table 3. Pressure (P1) Side Delineation

Part Number	Case Type	Pressure (P1) Side Identifier
MPX2010D	344	Stainless Steep Cap
MPX2010DP	344C	Side with Part Marking
MPX2010GP	344B	Side with Port Attached
MPX2010GS	344E	Side with Port Attached
MPX2010GSX	344F	Side with Port Attached
MPXV2010GP	1369	Side with Port Attached
MPXV2010DP	1351	Side with Part Marking

PACKAGE DIMENSIONS



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION -A- IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED 16.00 (0.630).

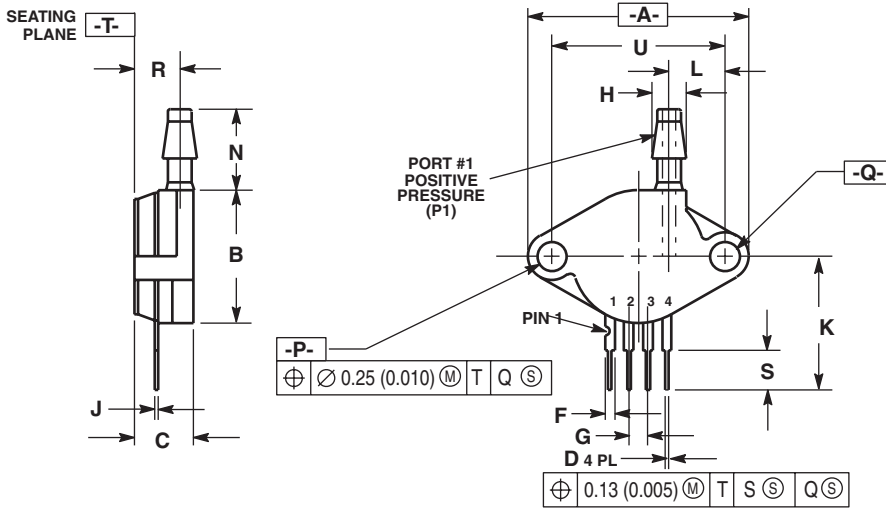
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.595	0.630	15.11	16.00
B	0.514	0.534	13.06	13.56
C	0.200	0.220	5.08	5.59
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.40
L	0.695	0.725	17.65	18.42
M	30° NOM		30° NOM	
N	0.475	0.495	12.07	12.57
R	0.430	0.450	10.92	11.43
Y	0.048	0.052	1.22	1.32
Z	0.106	0.118	2.68	3.00

STYLE 1:
PIN 1. GROUND
2. + OUTPUT
3. + SUPPLY
4. - OUTPUT

STYLE 2:
PIN 1. V_{CC}
2. - SUPPLY
3. + SUPPLY
4. GROUND

STYLE 3:
PIN 1. GND
2. -VOUT
3. VS
4. +VOUT

CASE 344-15 ISSUE AA UNIBODY PACKAGE



NOTES:

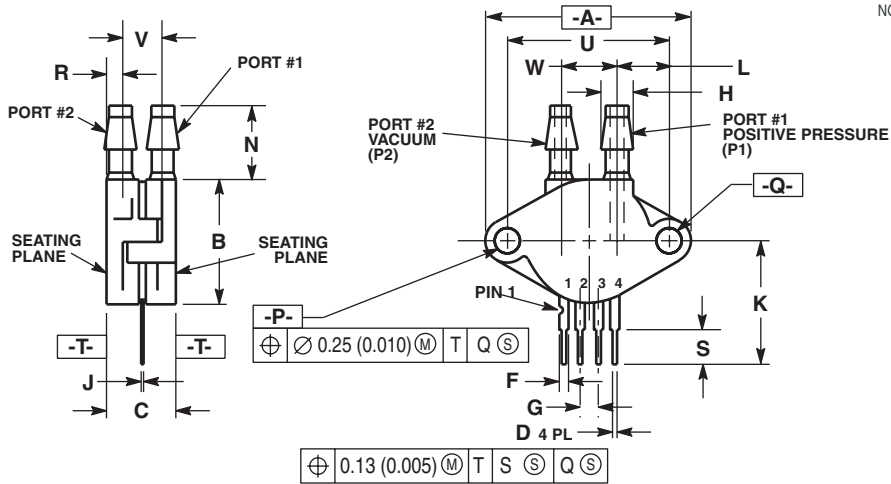
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.305	0.325	7.75	8.26
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
H	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.230	0.250	5.84	6.35
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	

STYLE 1:
PIN 1. GROUND
2. + OUTPUT
3. + SUPPLY
4. - OUTPUT

CASE 344B-01 ISSUE B UNIBODY PACKAGE

PACKAGE DIMENSIONS

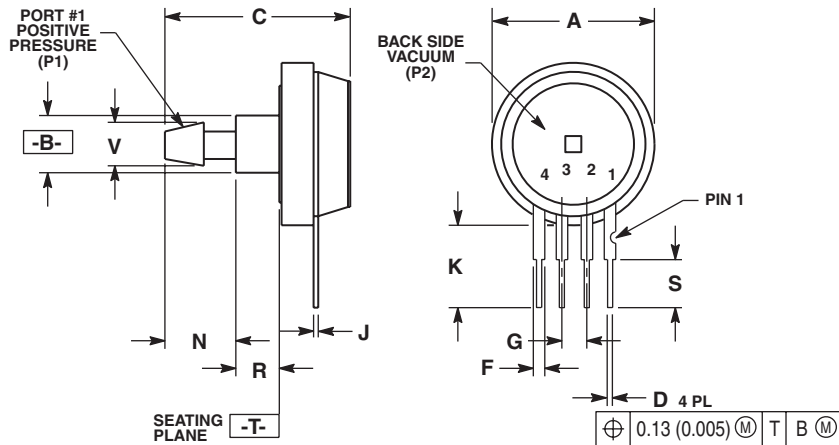


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.405	0.435	10.29	11.05
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
H	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.063	0.083	1.60	2.11
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	
V	0.248	0.278	6.30	7.06
W	0.310	0.330	7.87	8.38

- STYLE 1:
 PIN 1. GROUND
 2. + OUTPUT
 3. + SUPPLY
 4. - OUTPUT

CASE 344C-01 ISSUE B UNIBODY PACKAGE



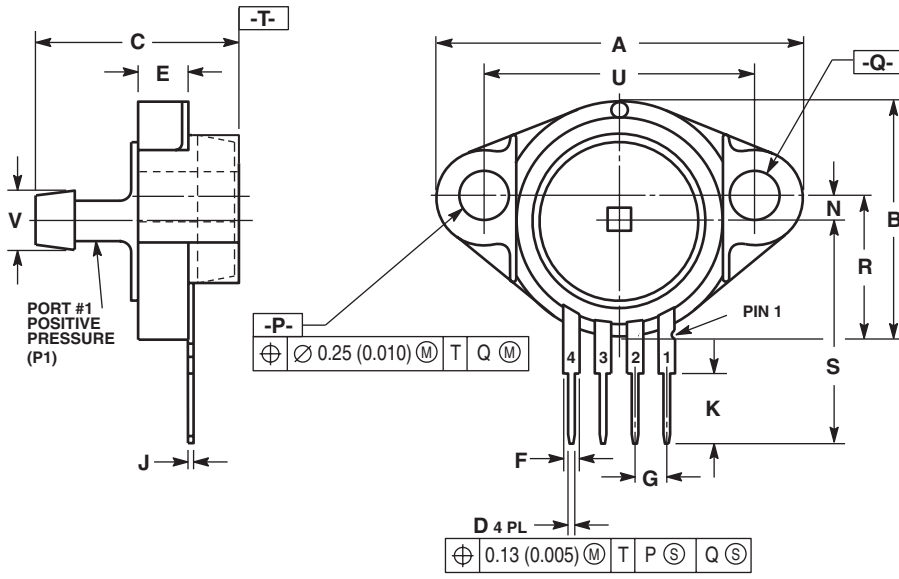
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.690	0.720	17.53	18.28
B	0.245	0.255	6.22	6.48
C	0.780	0.820	19.81	20.82
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.41
K	0.345	0.375	8.76	9.53
N	0.300	0.310	7.62	7.87
R	0.178	0.186	4.52	4.72
S	0.220	0.240	5.59	6.10
V	0.182	0.194	4.62	4.93

- STYLE 1:
 PIN 1. GROUND
 2. + OUTPUT
 3. + SUPPLY
 4. - OUTPUT

CASE 344E-01 ISSUE B UNIBODY PACKAGE

PACKAGE DIMENSIONS



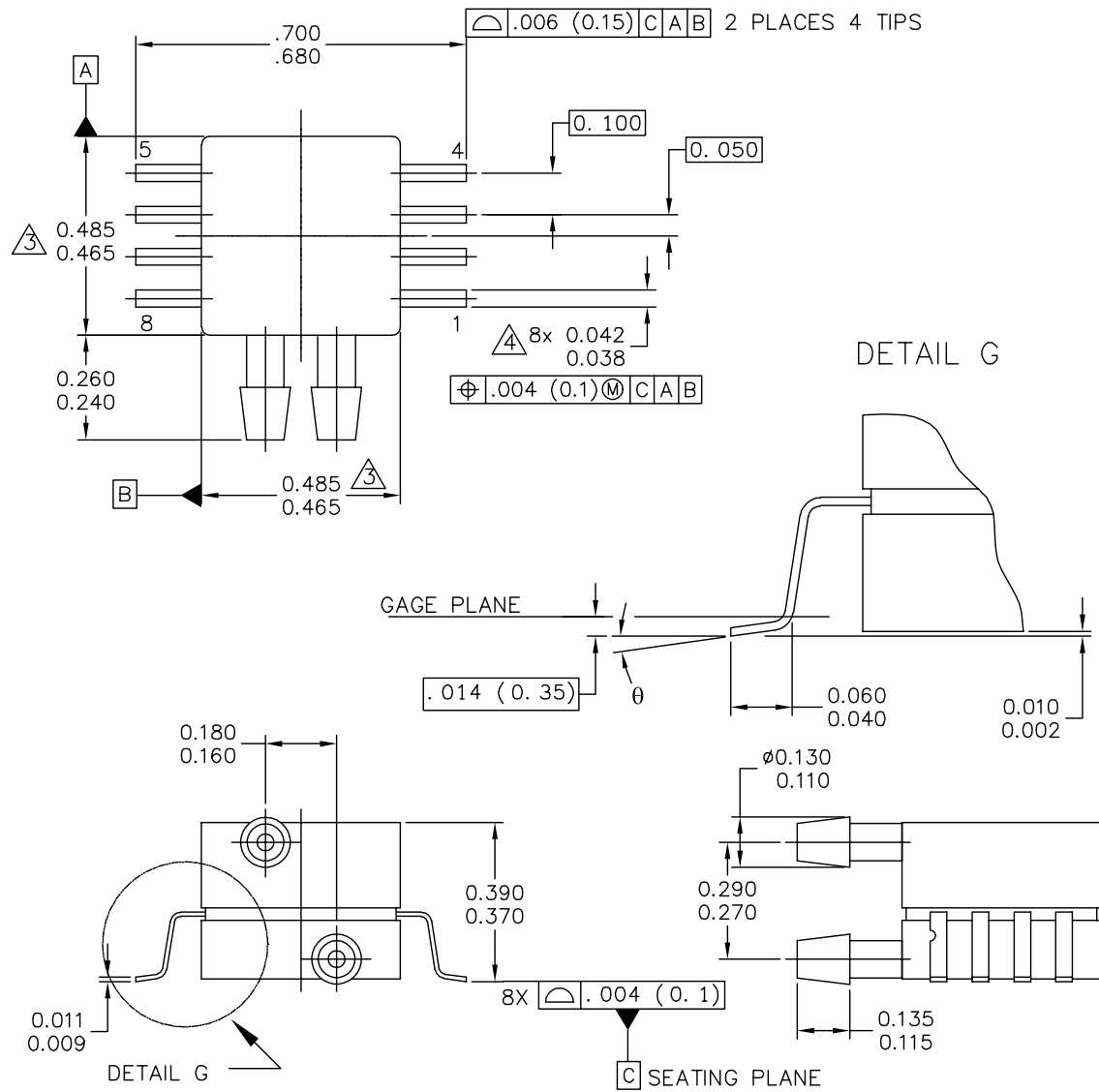
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.080	1.120	27.43	28.45
B	0.740	0.760	18.80	19.30
C	0.630	0.650	16.00	16.51
D	0.016	0.020	0.41	0.51
E	0.160	0.180	4.06	4.57
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.41
K	0.220	0.240	5.59	6.10
N	0.070	0.080	1.78	2.03
P	0.150	0.160	3.81	4.06
Q	0.150	0.160	3.81	4.06
R	0.440	0.460	11.18	11.68
S	0.695	0.725	17.65	18.42
U	0.840	0.860	21.34	21.84
V	0.182	0.194	4.62	4.92

- STYLE 1:
 PIN 1. GROUND
 2. V (+) OUT
 3. V SUPPLY
 4. V (-) OUT

CASE 344F-01 ISSUE B UNIBODY PACKAGE

PACKAGE DIMENSIONS



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TITLE: 8 LD SNR, DUAL PORT	DOCUMENT NO: 98ASA99255D	REV: A	
	CASE NUMBER: 1351-01	27 JUL 2005	
	STANDARD: NON-JEDEC		

PAGE 1 OF 2

CASE1351-01 ISSUE A SMALL OUTLINE PACKAGE

MPX2010

PACKAGE DIMENSIONS

NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 PER SIDE.
4. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

STYLE 1:

PIN 1: GND
 PIN 2: +Vout
 PIN 3: Vs
 PIN 4: -Vout
 PIN 5: N/C
 PIN 6: N/C
 PIN 7: N/C
 PIN 8: N/C

STYLE 2:

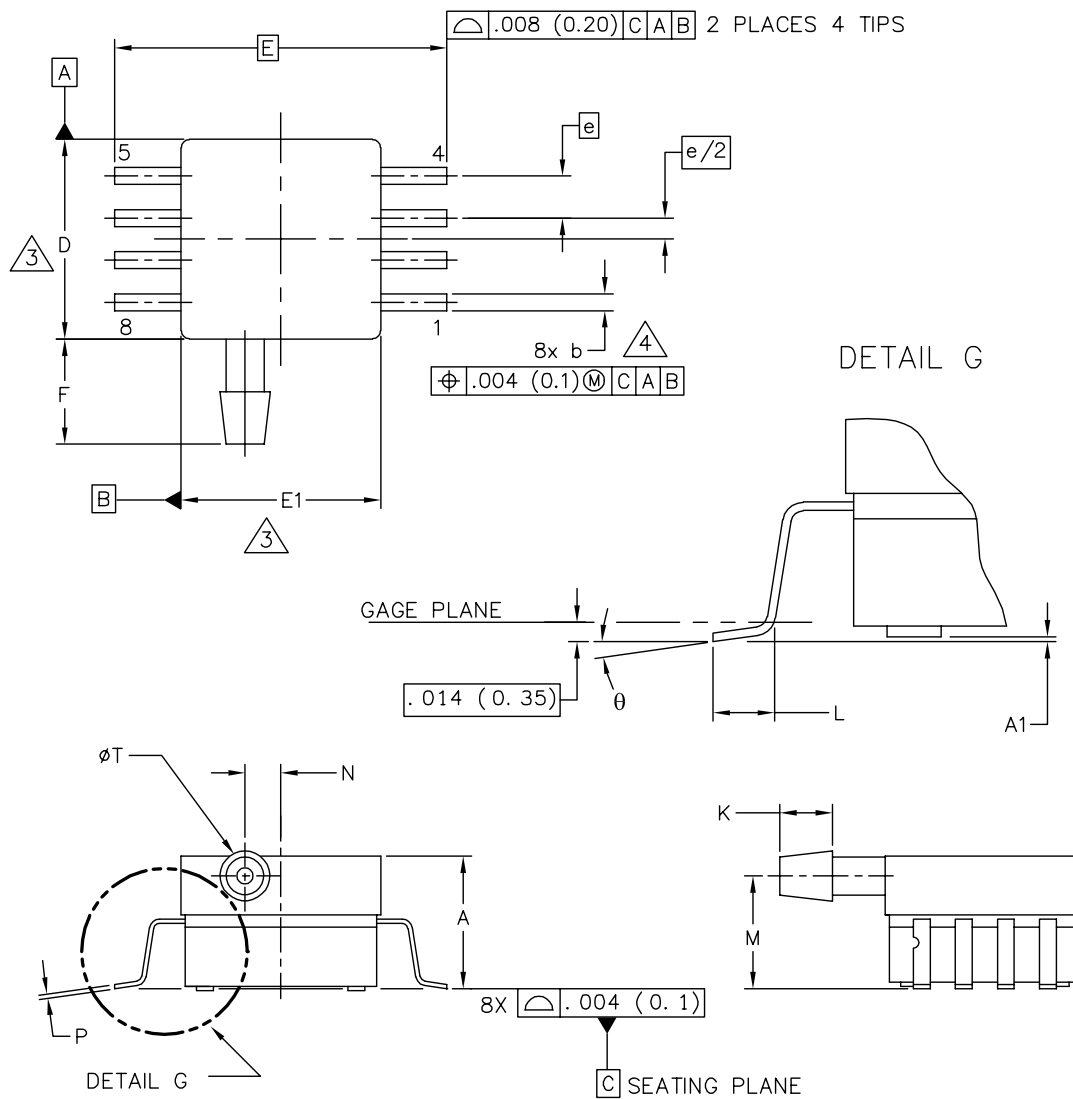
PIN 1: N/C
 PIN 2: Vs
 PIN 3: GND
 PIN 4: Vout
 PIN 5: N/C
 PIN 6: N/C
 PIN 7: N/C
 PIN 8: N/C

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TITLE: 8 LD SNSR, DUAL PORT	DOCUMENT NO: 98ASA99255D	REV: A
	CASE NUMBER: 1351-01	27 JUL 2005
	STANDARD: NON-JEDEC	

PAGE 2 OF 2

**CASE1351-01
 ISSUE A
 SMALL OUTLINE PACKAGE**

PACKAGE DIMENSIONS



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			DOCUMENT NO: 98ASA99303D	REV: B
TITLE: 8 LD SOP, SIDE PORT	CASE NUMBER: 1369-01		24 MAY 2005	
	STANDARD: NON-JEDEC			

PAGE 1 OF 2

**CASE 1369-01
ISSUE B
SMALL OUTLINE PACKAGE**

MPX2010

PACKAGE DIMENSIONS

NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
- ③ DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 (0.152) PER SIDE.
- ④ DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 (0.203) MAXIMUM.

DIM	INCHES		MILLIMETERS		DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.300	.330	7.11	7.62	θ	0°	7°	0°	7°
A1	.002	.010	0.05	0.25	-	---	---	---	---
b	.038	.042	0.96	1.07	-	---	---	---	---
D	.465	.485	11.81	12.32	-	---	---	---	---
E	.717 BSC		18.21 BSC		-	---	---	---	---
E1	.465	.485	11.81	12.32	-	---	---	---	---
e	.100 BSC		2.54 BSC		-	---	---	---	---
F	.245	.255	6.22	6.47	-	---	---	---	---
K	.120	.130	3.05	3.30	-	---	---	---	---
L	.061	.071	1.55	1.80	-	---	---	---	---
M	.270	.290	6.86	7.36	-	---	---	---	---
N	.080	.090	2.03	2.28	-	---	---	---	---
P	.009	.011	0.23	0.28	-	---	---	---	---
T	.115	.125	2.92	3.17	-	---	---	---	---
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TITLE: 8 LD SOP, SIDE PORT					DOCUMENT NO: 98ASA99303D			REV: B	
					CASE NUMBER: 1369-01			24 MAY 2005	
					STANDARD: NON-JEDEC				

PAGE 2 OF 2

**CASE 1369-01
ISSUE B
SMALL OUTLINE PACKAGE**

NOTES

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